

METHOD AND APPARATUS FOR JOINING PROTECTIVE TAPE TO SEMICONDUCTOR WAFER
ABSTRACT OF THE DISCLOSURE

A method for joining a protective tape to a semiconductor wafer includes the steps of: mounting a semiconductor wafer, which has a surface with a pattern formed thereon, on a holding member; joining a protective tape, which protects the pattern, to the surface of the semiconductor wafer and, also, to a surface of an outer peripheral member disposed around the holding member; and cutting out the protective tape along an outer circumference of the semiconductor wafer. The holding member and the outer peripheral member are disposed on a holding table, which holds the semiconductor wafer, so as to be adjacent to each other, and the outer peripheral member is formed from a member which is different from that of the holding table.

(Fig. 3)